



DT1446-04SO

August 2014

4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY

Product Summary

V _{BR (min)}	I _{PP (max)}	C _{T (typ)}
6V	4.7A	0.55pF

Description

The DT1446-04SO is a high performance device suitable for protecting four high speed I/Os and one V_{CC}. These devices are assembled in SOT26 package. They have high ESD surge capability and low capacitance.

Applications

Typically Used for High Speed Ports such as:

- **USB 2.0**
- IEEE1394
- **HDMI**
- Laptop and Personal Computers
- Flat Panel Displays
- Video Graphics Displays
- SIM Ports

Features

- IEC 61000-4-2 (ESD): Air ±19kV, Contact ±16kV
- Low Channel Input Capacitance of 0.55pF Max
- ESD Protection for four I/Os and one Vcc
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

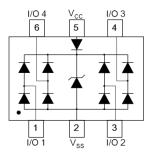
Mechanical Data

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020 (Lead Free Plating). Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.016 grams (approximate)

SOT26



Top View



Device Schematic

Ordering Information (Note 4)

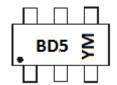
Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DT1446-04SO-7	Standard	BD5	7	8	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.



Marking Information



BD5 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	2013	2014	2015	2016	2017	2018
Code	А	В	С	D	E	F

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current ,per IEC 61000-4-5	I _{PP_I/O}	4.7	Α	I/O to V _{SS} , 8/20µs
Operating Voltage (DC)	V_{DC}	6	V	V _{CC} to V _{SS}
ESD Protection – Contact Discharge	V _{ESD_I/O}	±16	kV	I/O to V _{SS} , per IEC 61000-4-2
Lob Flotection - Contact Discharge	$V_{ESD}V_{CC}$	±30	kV	V _{CC} to V _{SS} , per IEC 61000-4-2
ESD Protection – Air Discharge, per IEC 61000-4-2	V _{ESD_I/O}	±19	kV	I/O to V _{SS} , per IEC 61000-4-2
230 Frotection – All bischarge, per IEC 01000-4-2	$V_{ESD}V_{CC}$	±30	kV	V _{CC} to V _{SS} , per IEC 61000-4-2

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation Typical (Note 5)	P _D	300	mW
Thermal Resistance, Junction to Ambient Typical (Note 5)	$R_{\theta JA}$	417	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	Vrwm	_	_	5.0	V	V _{CC} to V _{SS}
Reverse Current (Note 6)	I _R (V _{CC} to V _{SS)}	_	_	5.0	μΑ	V _R = V _{RWM} = 5V, V _{CC} to V _{SS}
Reverse Current (Note 6)	I _{R(IO} to V _{SS)}	_	_	1.0	μA	$V_R = V_{RWM} = 5V$, any I/O to V_{SS}
Reverse Breakdown Voltage	VBR	6.0	_	9.0	V	I _R = 1mA, V _{CC} to V _{SS}
Forward Clamping Voltage	V _F	_	0.8	1.0	V	I _F = 15mA, V _{SS} to V _{CC}
Reverse Clamping Voltage (Note 7)	V _{C_I/O}	_	8.5	_	V	I _{PP} =4.7A, I/O to V _{SS} , 8/20μS
ESD Clamping Voltage	V _{ESD} _V _{CC}	_	10	_	V	TLP, 20A, $tp = 100 \text{ ns}$, V_{CC} to V_{SS}
L3D Clamping Voltage	V _{ESD} _I/O	_	12	_	V	TLP, 20A, $tp = 100 \text{ ns}$, I/O to V_{SS}
Dynamic Resistance	R _{DIF} _V _{CC}	_	0.14	_	Ω	TLP, 20A, $tp = 100 \text{ ns}$, V_{CC} to V_{SS}
Dynamic Resistance	R _{DIF_I/O}	_	0.3	_	Ω	TLP, 20A, $tp = 100 \text{ ns}$, I/O to V_{SS}
Channel Input Capacitance	C _{I/O} to V _{SS}	_	0.55	0.65	pF	$V_R = 2.5V, V_{CC} = 5V, f = 1MHz$
Channel Input Capacitance	C _{I/O} to V _{SS}		0.65	_	pF	$V_R = 2.5V$, $V_{CC} = $ floating, $f = 1MHz$
Variation of Channel Input Capacitance	C _{I/OMAX} -C _{I/OMIN}	_	0.03	_	pF	$V_{CC} = 5V$, $V_{SS} = 0V$, $I/O = 2.5V$, $f = 1MHz$, $T = +25^{\circ}C$, $C_{I/OMAX} - C_{I/OMIN}$
Variation of Channel Input Capacitance	CI/OMAX-CI/OMIN	_	0.05	_	pF	V_{CC} =floating , V_{SS} = 0V, I/O = 2.5V, f = 1MHz, T = +25°C , $C_{I/OMAX}$ - $C_{I/OMIN}$

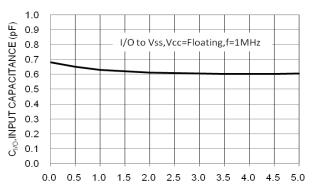
Notes:

- 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.
- 6. Short duration pulse test used to minimize self-heating effect.
- 7. Clamping voltage value is based on an $8x20\mu s$ peak pulse current (I_{pp}) waveform.

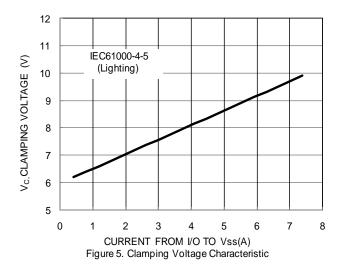


100 BEAK PULSE DERATING IN % ON CURRENT OF STATE OF STATE

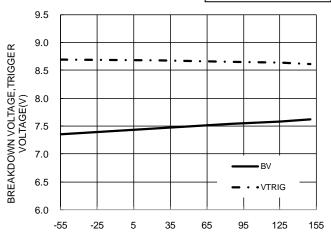
T_A,AMBIENT TEMPERATURE(°C) Figure1. Pulse Derating Curve



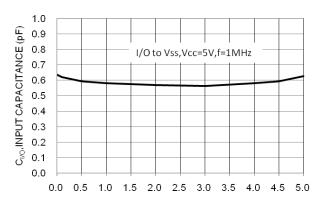
V_{I/0,} INPUT VOLTAGE (V) Figure 3. Input Capacitance vs. Input Voltage



DT1446-04SO



T_A, AMBIENT TEMPERATURE (°C) Figure 2. BV, Trigger Voltage vs. Ambient Temperature



V_{I/O,} INPUT VOLTAGE (V) Figure 4. Input Capacitance ∨s. Input Voltage

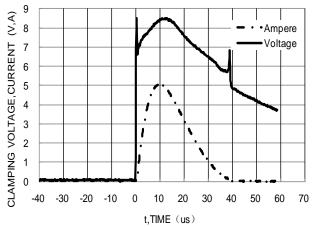
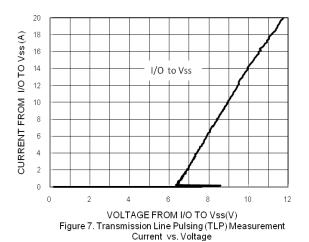
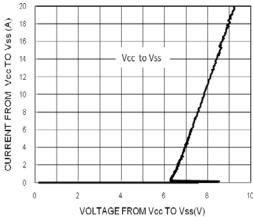


Figure 6. Waveform of Clamping Voltage, Current vs. Time(8/20us, I/O to Vss)



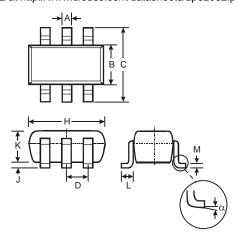




VOLTAGE FROM Vcc TO Vss(V)
Figure 8. Transmission Line Pulsing (TLP) Measurement
Current vs. Voltage

Package Outline Dimensions

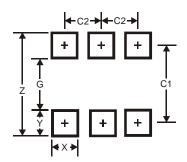
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SOT26							
Dim	Min	Max	Тур					
Α	0.35	0.50	0.38					
В	1.50	1.70	1.60					
U	2.70	3.00	2.80					
D	_		0.95					
Н	2.90	3.10	3.00					
J	0.013	0.10	0.05					
K	1.00	1.30	1.10					
L	0.35	0.55	0.40					
M	0.10	0.20	0.15					
a	0°	8°						
All D	imensi	ons in	mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Υ	0.80
C1	2.40
C2	0.95



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